

Title of Change:	CAT25320 FAB Transfer LAPIS (formerly OKI) to Gresham.
Proposed First Ship date:	23 March 2020
Contact Information:	Contact your local ON Semiconductor Sales Office or < Ovidiu.Tol@onsemi.com >
Samples:	Contact your local ON Semiconductor Sales Office or < PCN.Samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >
Change Part Identification:	Marking Style will be change and the CS code (Custom Source 2 digit country code of wafer fabrication) on the label will be changed from JP to US.
Change Category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>Mark</u>

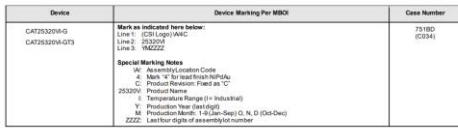



Change Sub-Category(s):

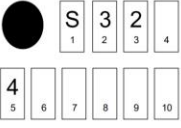
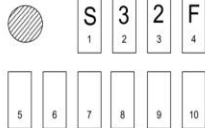

<input type="checkbox"/> Manufacturing Site Addition	<input type="checkbox"/> Material Change	<input checked="" type="checkbox"/> Datasheet/Product Doc change
<input checked="" type="checkbox"/> Manufacturing Site Transfer	<input type="checkbox"/> Product specific change	<input checked="" type="checkbox"/> Shipping/Packaging/Marking
<input type="checkbox"/> Manufacturing Process Change		<input type="checkbox"/> Other: _____

Sites Affected:	ON Semiconductor Sites: ON Semiconductor, Philippines ON Semiconductor Gresham, Oregon, US	External Foundry/Subcon Sites: Subcons Thailand External Foundry Japan
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Description and Purpose:
Qualify new die source for CAT25320 to support customer demand. All material no changes except Die Source.

	Before Change Description	After Change Description
Die Source	Foundry in Japan	ON Semiconductor Fab in Oregon US

	From	To
CAT25320VI-GT3 Product marking change	 <p>Front Side Mark:</p>  <p>Back Side Mark: None</p>	 

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Datasheet change:

The original datasheet will be left active on the www.onsemi.com customer web site for comparison purposes until the FPCN expires. The new datasheet will become visible on the web site on that FPCN expiration.

Qualification Plan:

QV DEVICE NAME: **CAT25320VI-GT3**

RMS : **60123;60918**

PACKAGE : **8L SOIC**

Test	Specification	Condition	Interval
EDR/HTSL	AEC Q100-005	Endurance preconditioning - 1 Mil cycles@ Room temp, High Temp Data Retention: Ta=150°C for 1008 hrs.	1008 hrs
HTOL	JA108	TA=150C, bias at 1.2X Nominal (not to exceed Max rated) (NVM endurance 1 Million cycle preconditioning must be performed prior to HTOL stress.)	1008 hrs
ELFR	AECQ100-008	TA=150C, bias at 1.2X Nominal (not to exceed Max rated)	24 hrs
PC	J STD 020A, JESD22-A113	Solder reflow MSL 1 at 260C	
HAST	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 100% of rated V or 100V max	96 hrs
TC	JESD22-A104	Temp = -65°C to +150°C	500 cycles
UHASt	JESD22-A118	Temp = 130C, RH=85%, ~18.8 psig	96 hrs
SAT	12MSB17722C	Scanning Acoustical Topography ,Pre post MSL, TC500	
CDPA WP	12MSB17722C	Custom Destructive Physical Analysis - Wire Pull Post TC	

Estimated date for qualification completion: 25 October 2019

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
CAT25320VI-GT3	CAT25320VI-GT3
CAT25320VI-GT3	CAT25320VI-GT3

Japanese translation of the notification starts here.
通知の日本語訳はここから始まります。

Note: The Japanese version is for reference only. In case of any differences between the English and Japanese version, the English version shall control.

注：日本語版は参照用です。英語版と日本語版の違いがある場合は、英語版が優先されます。



初回製品 / プロセス変更通知

文書番号# : IPCN22812X

発行日 : 10 September 2019

変更件名:	CAT25320 FAB を LAPIS (以前の OKI) からグreshamに移管
初回出荷予定日:	23 March 2020
連絡先情報:	現地のオン・セミコンダクター営業所または <Ovidiu.Tol@onsemi.com> にお問い合わせください。
サンプル:	現地のオン・セミコンダクター営業所または <PCN.Samples@onsemi.com> にお問い合わせください。 サンプルは、この変更の初回通知、初回 PCN の日付から 30 日以内に要求してください。 サンプル納入時は、依頼日、数量、特別梱包材/ラベル条件によって異なります。
通知種別:	これは、お客様宛の初回製品 / プロセス変更通知 (IPCN) です。IPCN は、近日中に実施される変更に関する事前通知であり、変更の詳細および影響を受けるデバイスについての一般情報が記載されます。また、暫定的な信頼性認証計画も記載されます。 最終的な認定データおよび特性データは最終製品 / プロセス変更通知 (FPCN) に含まれます。この IPCN は、変更実施から少なくとも 90 日前に発行される最終製品 / プロセス変更通知 (FPCN) に先だって通知されます。ご不明な点がありましたら、<PCN.Support@onsemi.com> にお問い合わせください。
変更部品の識別:	マーキングスタイルが変更され、さらにラベル上の CS コード (ウェハ製造のカスタムソース 2 桁の国コード) は JP から US に変更されます。
変更カテゴリ:	<input checked="" type="checkbox"/> ウェハファブの変更 <input type="checkbox"/> アセンブリの変更 <input type="checkbox"/> 試験の変更 <input checked="" type="checkbox"/> その他 Mark

変更サブカテゴリ:	<input type="checkbox"/> 製造拠点の追加 <input type="checkbox"/> 材料の変更 <input checked="" type="checkbox"/> データシート/製品資料の変更 <input checked="" type="checkbox"/> 製造拠点の移転 <input type="checkbox"/> 製品仕様の変更 <input checked="" type="checkbox"/> 出荷/パッケージング/表記 <input type="checkbox"/> 製造プロセスの変更 <input type="checkbox"/> その他: _____
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影響を受ける拠点:	オン・セミコンダクター拠点: ON Semiconductor, Philippines ON Semiconductor Gresham, Oregon, US	外部製造工場 / 下請業者拠点: Subcons Thailand External Foundry Japan
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説明および目的:
 顧客需要に対応して、CAT25320 の新しいダイソースを認定します。ダイソースを除き、材料変更はありません。

	変更前の表記	変更後の表記
ダイソース	Foundry in Japan	ON Semiconductor Fab in Oregon US

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CAT25320VI-GT3 製品マーキング変更	<table border="1"> <thead> <tr> <th>Device</th> <th>Device Marking Per M80K</th> <th>Case Number</th> </tr> </thead> <tbody> <tr> <td>CAT25320A-G CAT25320A-GT3</td> <td> Mark as indicated here below: Line 1: CSI logo M80K Line 2: 2320M Line 3: MZZZ Special Marking Notes: M: Assembly Location Code Z: Mark "K" for used from M80Ks C: Product Revision: Fixed as "C" 25320V Y: Production Year (year digit) M: Production Month: 1-9 (Jan-Sep) O, N, D (Oct-Dec) ZZZZ: Last four digits of assembly lot number </td> <td>7518D (0034)</td> </tr> </tbody> </table> <p>Front Side Mark:</p> <p>Back Side Mark: None</p>	Device	Device Marking Per M80K	Case Number	CAT25320A-G CAT25320A-GT3	Mark as indicated here below: Line 1: CSI logo M80K Line 2: 2320M Line 3: MZZZ Special Marking Notes: M: Assembly Location Code Z: Mark "K" for used from M80Ks C: Product Revision: Fixed as "C" 25320V Y: Production Year (year digit) M: Production Month: 1-9 (Jan-Sep) O, N, D (Oct-Dec) ZZZZ: Last four digits of assembly lot number	7518D (0034)	<table border="1"> <thead> <tr> <th>Device</th> <th>Device Marking Per M80K</th> <th>Case Number</th> </tr> </thead> <tbody> <tr> <td>CAT25320VI-GT3F</td> <td> Mark as indicated here below: Line 1: 2320F Line 2: *YMAAA (* = assembly site code) Y: Production Year (last digit) M: Production Month: 1-9 (Jan-Sep) O, N, D (Oct-Dec) AAA: last 3 characters of assembly lot number ●: Pin-free microdot </td> <td>7518D (0034)</td> </tr> </tbody> </table>	Device	Device Marking Per M80K	Case Number	CAT25320VI-GT3F	Mark as indicated here below: Line 1: 2320F Line 2: *YMAAA (* = assembly site code) Y: Production Year (last digit) M: Production Month: 1-9 (Jan-Sep) O, N, D (Oct-Dec) AAA: last 3 characters of assembly lot number ●: Pin-free microdot	7518D (0034)
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データシート変更:

元のデータシートは、FPCN の有効期限が切れるまで、比較目的でお客様向け Web サイト(www.onsemi.com)に掲載したままになります。新しいデータシートは、その FPCN の有効期限が切れた時点で、Web サイト上で閲覧可能になります。

認定計画:

デバイス名: CAT25320VI-GT3

RMS: 60123;60918

パッケージ: 8L SOIC

テスト	仕様	条件	間隔
EDR/HTSL	AEC Q100-005	Endurance preconditioning - 1 Mil cycles@ Room temp, High Temp Data Retention: Ta=150°C for 1008 hrs.	1008 hrs
HTOL	JA108	TA=150C, bias at 1.2X Nominal (not to exceed Max rated) (NVM endurance 1 Million cycle preconditioning must be performed prior to HTOL stress.)	1008 hrs
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SAT	12MSB17722C	Scanning Acoustical Topography ,Pre post MSL, TC500	
CDPA WP	12MSB17722C	Custom Destructive Physical Analysis - Wire Pull Post TC	

認定完了予定日 : 25 October 2019

影響を受ける部品の一覧:

注: 部品一覧には標準部品番号 (既製品) のみが記載されています。本 PCN の影響を受けるカスタム部品番号は、PCN メールで提供される顧客個別の付録、または PCN カスタマイズポータルに記載されています。

部品番号	認定試験用ピークル
CAT25320VI-GT3	CAT25320VI-GT3
CAT25320VI-GT3	CAT25320VI-GT3